

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	((carrier substrate pcb ((circuit wiring near1 board)) with (ic (integrated adj circuit) chip die (semiconductor near1 (device element))) with (bump ball (solder adj conntector)) with ((compress\$4 near1 (film layer material)) rubber foam) with ((insulat\$3 dielectric) near (material underfill layer))).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 10:03
L2	3	((carrier substrate pcb ((circuit wiring near1 board)) same (ic (integrated adj circuit) chip die (semiconductor near1 (device element))) same (bump ball (solder adj conntector)) same ((compress\$4 near1 (film layer material)) rubber foam) same ((insulat\$3 dielectric) near (material underfill layer))).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 09:46
L3	36	((carrier substrate pcb ((circuit wiring near1 board)) and (ic (integrated adj circuit) chip die (semiconductor near1 (device element))) and (bump ball (solder adj conntector)) and ((compress\$4 near1 (film layer material)) rubber foam) and ((insulat\$3 dielectric) near (material underfill layer))).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 10:14
L4	9146	257/738,778-780,e23.021,e23.023.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 10:02
L5	5638	438/108,612-613.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 10:02
L6	13210	4 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 10:02

## EAST Search History

L7	9349	6 and (carrier substrate pcb ((circuit wiring) near1 board)) and (ic (integrated adj circuit) chip die (semiconductor near1 (device element))) and (bump ball (solder adj conntector))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 10:10
L8	2827	7 and (((compress\$4 near1 (film layer material)) rubber foam (underfill\$2 (under adj fill\$2)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 10:13
L9	93	8 and (((compress\$4 near1 (film layer material)) rubber foam (underfill\$2 (under adj fill\$2))) with surround\$3 with (bump ball (solder adj conntector)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 10:16
L10	1	("6535237").URPN.	USPAT	OR	ON	2007/09/13 10:47
L11	27	("4500895"   "4550612"   "4680859"   "4695853"   "4862197"   "5016023"   "5070410"   "5133495"   "5203075"   "5227812"   "5278584"   "5279711"   "5323084"   "5369880"   "5433995"   "5439956"   "5442384"   "5453581"   "5539153"   "5543585"   "5545465"   "5583747"   "5777576"   "6017117"   "6113216"   "6135586"   "6228681").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/13 10:47